IC Packaging: Allegro® X Advanced Package Designer

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Contents

IC Packaging: Allegro X Advanced Package Designer Help. 5

IC Packaging: Allegro X Advanced Package Designer

4

IC Packaging: Allegro X Advanced Package Designer Help

Choose Help - Documentation or click $\underline{APD\ Help}$ to view the documentation associated with Allegro X Advanced Package Designer (APD) in Cadence Doc Assistant.